

AMTECH

Advanced SMT Solder Products

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An ISO 9001 Certified Company

Product Data Sheet

NC-560-TF (Tacky Flux)

Product Description

- Can be used with low melting alloys
- Can be used with leaded or lead-free alloys
- Complies with RoHS II
- Excellent wetting compatibility with most board finishes
- Ideal for rework, BGA, PGA and CSP packages
- Flux classification is ROL0

Solder Alloy Systems

NC-560-TF can be used with the following alloys.
(E) Eutectic

Alloy	Liquidus
Sn42/Bi58	(E) 138°C
Sn43/Pb43/Bi14	144°C
Sn62/Pb36/Ag2	179°C
Sn63/Pb37	(E) 183°C
Sn60/Pb40	191°C
Sn95.5/Ag4.0/Cu.5	219°C
Sn96.5/Ag3.0/Cu.5	219°C
Sn96.5/Ag3.5	(E) 221°C
Sn99/Ag.3/Cu.7	227°C
Sn99.3.Cu.7	(E) 227°C
Sn100	(E) 232°C
Sn95/Sb5	240°C
Sn95/Ag5	245°C

Tack Time

Will remain tacky for 48 hours.

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA) works well.

Storage and Handling Procedures

Refrigerated storage at 5 and 25°C will prolong Tacky Flux's shelf life to no less than 1 year. Syringes & cartridges should be stored vertically with the dispensing tip down. Tacky Paste Flux should be allowed to reach ambient temperature naturally, prior to use (about 6-8 hours). NEVER FREEZE TACKY PASTE FLUX.

Available Packaging

Standard packaging for stencil printing and dispensing applications include:
75 & 150 gram jars
150 gram cartridges
10cc & 30cc syringes

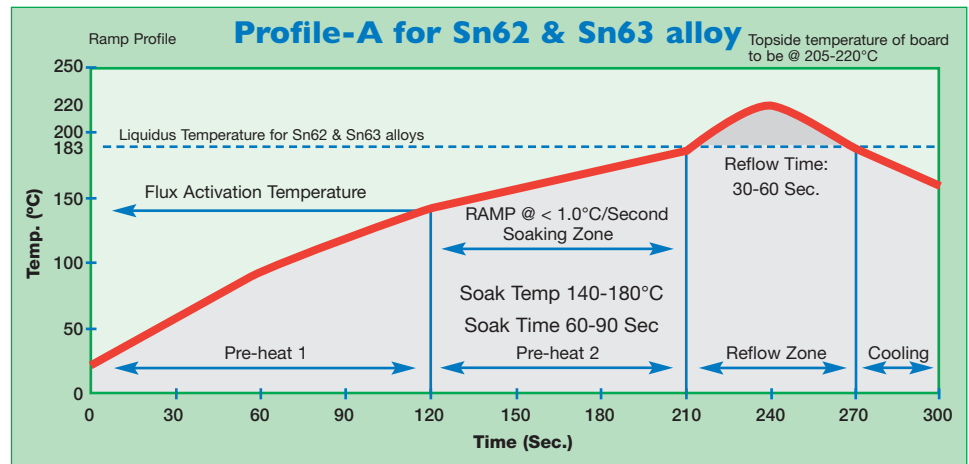
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NC-560-HF-TF (Tacky Flux)

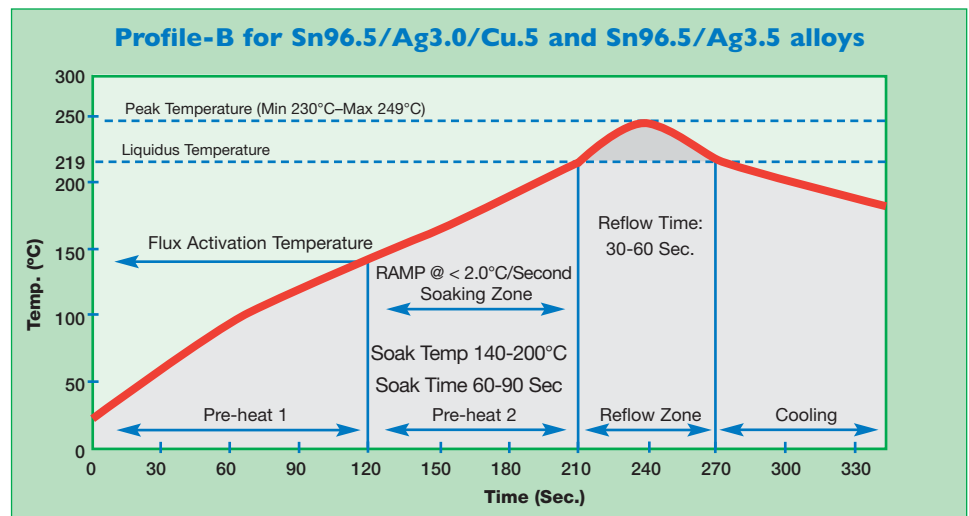
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Recommended Profiles:

Profile-A was designed to serve as a starting point for process optimization using Tacky Paste Flux. A cool down rate of (-) 2–4°C/second is ideal for the formation of a fine grain structure without risking damage to thermally sensitive components. This profile is recommended when soldering Sn63 or Sn62 alloys.



Profile-B was designed to serve as a starting point for process optimization using Tacky Paste Flux. A cool down rate of (-) 2 - 4°C/second is ideal for the formation of a fine grain structure without risking damage to thermally sensitive components. This profile is recommended when soldering Sn96.5/Ag3.0/Cu.5 or Sn96.5/Ag3.5 alloys.



The information contained herein is based on technical data that we believe to be reliable and is intended for use by persons having technical skill, at their own risk. Users of our products should make their own tests to determine the suitability of each product for their particular process. AMTECH will assume no liability for results obtained or damages incurred through the application of the data presented.

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